## MAR 3 1 2006 W

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

DALSON YE SENG KIM JEFFREY TOH TUCK FOOK LEE CHOON KUAN

SERIAL NO. 10/797,807

EXAMINER: ROSE, KIESHA L.

Filing Date:

03-10-2004

ART UNIT: 2822

For:

METHOD FOR FABRICATING SEMICONDUCTOR

COMPONENT WITH CHIP ON BOARD LEADFRAME

DOCKET NO. 02-1467.1

TRANSMITTAL LETTER March 27, 2006

Mail Stop Issue Fee Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

Sir:

Enclosed for filing in the above application are the following:

- 1. Issue Fee Transmittal
- 2. A check in the amount of \$1709.00 for the issue fee, publication fee and printed copies (3)
- 3. "Fee Address" Indication Form
- 4. A return receipt postcard

Respectfully submitted:

Stephen 3. Grotton, Registration No. 28,418

Attorney of Record 2764 South Braun Way Lakewood, CO 80228 Telephone: (303) 989 6353

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Mail Stop Issue Fee, Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on this 27th day of March, 2006.

March 27, 2006 Date of Signature

Stephen A. Oratton

, Attorney of Record